STARPOWER

SEMICONDUCTOR™

GD800HFL120C3S

Molding Type Module

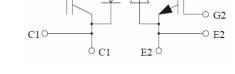
1200V/800A 2 in one-package

General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as general inverters and UPS.

Features

- High short circuit capability, self limiting to 6*I_C
- 10µs short circuit capability
- V_{CE(sat)} with positive temperature coefficient
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology



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E1 O-

G1O

C2 🖓

 \circ C2

Equivalent Circuit Schematic

Typical Applications

- AC inverter drives
- Switching mode power supplies
- Electronic welders

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5/20/2010

IGBT

Preliminary



Symbol	Description	GD800HFL120C3S	Units
V _{CES}	Collector-Emitter Voltage	1200	V
V _{GES}	Gate-Emitter Voltage	± 20	V
т	Collector Current (a) $T_C=25^{\circ}C$	1250	
I _C	(<i>a</i>) T _C =80 °C	800	A
I _{CM(1)}	Pulsed Collector Current $t_p = 1ms$	1600	Α
I _F	Diode Continuous Forward Current	800	Α
I _{FM}	Diode Maximum Forward Current	1600	Α
P _D	Maximum power Dissipation @ T _j =150°C	4310	W
T _{SC}	Short Circuit Withstand Time $@T_j=125^{\circ}C$	10	μs
Tj	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature Range	-40 to +125	°C
I ² t-value, Diode	$V_R=0V$, t=10ms, T _j =125 °C	140	kA ² s
V _{ISO}	Isolation Voltage RMS,f=50Hz,t=1min	2500	V
Mounting	Power Terminal Screw:M4	1.7 to 2.3	N.m
Torque	Power Terminal Screw:M8	8.0 to 10	19.111
	Mounting Screw:M6	4.25 to 5.75	N.m

Absolute Maximum Ratings $T_C=25$ °C unless otherwise noted

Notes:

(1) Repetitive rating: Pulse width limited by max. junction temperature

Electrical Characteristics of IGBT $T_C=25^{\circ}C$ unless otherwise noted

Off Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV _{CES}	Collector-Emitter	Ti=25℃	1200			V
	Breakdown Voltage	1 _j -23 C				v
I _{CES}	Callester Cut Off Current	V _{CE} =V _{CES} ,V _{GE} =0V,			5.0	mA
	Collector Cut-Off Current	T _j =25℃			5.0	
I _{GES}	Gate-Emitter Leakage	V _{GE} =V _{GES} ,V _{CE} =0V,			400	nA
	Current	Tj=25℃			400	

On Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V _{GE(th)}	Gate-Emitter Threshold Voltage	$I_C=32mA, V_{CE}=V_{GE},$ $T_j=25^{\circ}C$	5.0	6.2	7.0	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage	I_{C} =800A, V_{GE} =15V, T_{j} =25°C		1.8 2.0		V
		I_{C} =800A, V_{GE} =15V, T_{j} =125°C				v

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Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Q _{ge}	Gate charge	I _C =800A,V _{CE} =600V, V _{GE} =-15+15V		11.5		μC
t _{d(on)}	Turn-On Delay Time	V _{CC} =600V,I _C =800A,		600		ns
t _r	Rise Time	$R_{Gon}=3.3\Omega$,		230		ns
t _{d(off)}	Turn-Off Delay Time	$R_{Goff}=0.39\Omega$,		820		ns
t _f	Fall Time	$V_{GE} = \pm 15V, T_j = 25^{\circ}C$		150		ns
t _{d(on)}	Turn-On Delay Time			660		ns
t _r	Rise Time	V _{CC} =600V,I _C =800A,		220		ns
t _{d(off)}	Turn-Off Delay Time	$R_{Gon}=3.3\Omega$,		960		ns
t _f	Fall Time	$R_{Goff}=0.39\Omega$,		180		ns
Eon	Turn-On Switching Loss	$V_{GE} = \pm 15V, T_j = 125^{\circ}C$		160		mJ
E _{off}	Turn-Off Switching Loss			125		mJ
Cies	Input Capacitance			61.8		nF
C _{oes}	Output Capacitance	V _{CE} =25V,f=1MHz,		4.2		nF
C _{res}	Reverse Transfer Capacitance	V _{GE} =0V		2.7		nF
I _{SC}	SC Data	$\begin{array}{l} t_{S^{C}} \leqslant 10 \mu s, V_{GE} = 15 V, \\ T_{j} = 125 ^{\circ} C, V_{CC} = 900 V, \\ V_{CEM} \leqslant 1200 V \end{array}$		3760		А
L _{CE}	Stray Inductance			20		nH
R _{CC'+EE'}	Module lead resistance, terminal to chip	T _C =25℃		0.18		mΩ

Switching Characteristics

Electrical Characteristics of DIODE T_C=25°C unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units
17	Diode Forward	I	Tj=25℃		2.4		V
$V_{\rm F}$	Voltage	I _F =800A	Tj=125℃		2.2] `
Qr	Diode Reverse		Tj=25℃		37		μC
	Recovery Charge	I_F =800A, V_R =600V, di/dt=-3600A/µs, V_{GE} =-15V	Tj=125℃		90		
I _{RM}	Diode Peak		T _j =25℃		260		
	Reverse Recovery Current		T _j =125℃		400		А
E _{rec}	Reverse Recovery		T _j =25℃		9		mĪ
	Energy		Tj=125℃		24		mJ

Thermal Characteristics

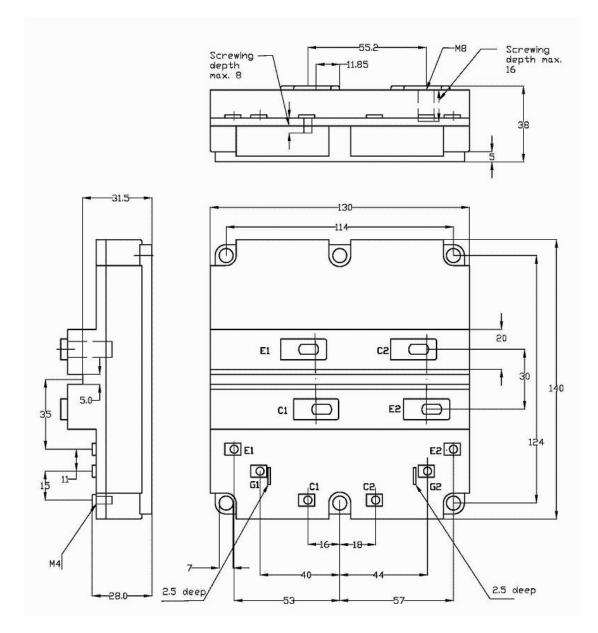
Symbol	Parameter		Max.	Units
$R_{\theta JC}$	Junction-to-Case (IGBT Part,per 1/2 Module)		0.029	K/W
$R_{\theta JC}$	Junction-to-Case (Diode Part,per 1/2 Module)		0.052	K/W
$R_{\theta CS}$	Case-to-Sink	0.006		K/W
	(conductive grease applied, per Module)	0.000		K/ W
Weight	Weight of Module	1500		g

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IGBT Module

Package Dimension

Dimensions in Millimeters



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